Stackpole Electronics, Inc.

Surface Mount High Current Jumper Chip Resistor

Resistive Product Solutions

Features:

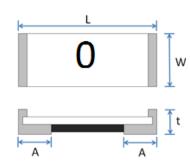
- Chip size from 0402 to 2512
- Max. resistance value less than 3 milliohm for 0402, less than 0.5 milliohm for all other sizes
- RoHS compliant lead free

Applications: •

- Switching power supply
- Voltage regulation module
- DC-DC converter, adaptor, battery pack, charger
- PDA and cell phone
- Power management applications



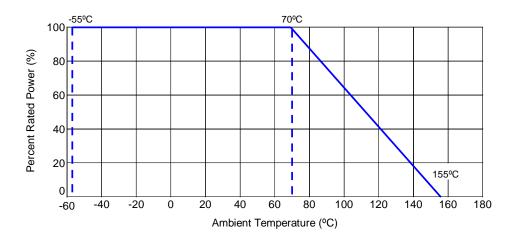
	Electrical S	pecifications	
Type / Code	Current Rating (A)	Operating Temperature Range	Ohmic Range (Ω)
0402	6.5		< 0.003
0603	22.4		
0805	31.6	-55°C to +155°C	< 0.0005
1206	38.7		< 0.0005
2512	63.2		



		Mechanical Spec	ifications		
Type / Code	L	W	t	A	Unit
0402	0.039 ± 0.004	0.020 ± 0.002	0.013 ± 0.002	0.010 ± 0.004	inches
	1.00 ± 0.10	0.50 ± 0.05	0.33 ± 0.05	0.25 ± 0.10	mm
0603	0.061 ± 0.004	0.031 ± 0.004	0.017 ± 0.004	0.014 ± 0.008	inches
	1.55 ± 0.10	0.80 ± 0.10	0.43 ± 0.10	0.35 ± 0.20	mm
0805	0.079 ± 0.006	0.049 ± 0.006	0.022 ± 0.004	0.014 ± 0.008	inches
	2.00 ± 0.15	1.25 ± 0.15	0.55 ± 0.10	0.35 ± 0.20	mm
1206	0.122 ± 0.008	0.061 ± 0.004	0.022 ± 0.004	0.016 ± 0.008	inches
	3.10 ± 0.20	1.55 ± 0.10	0.55 ± 0.10	0.40 ± 0.20	mm
2512	0.248 ± 0.008	0.126 ± 0.008	0.022 ± 0.004	0.020 ± 0.010	inches
	6.30 ± 0.20	3.20 ± 0.20	0.55 ± 0.10	0.50 ± 0.25	mm

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Power Derating Curve:

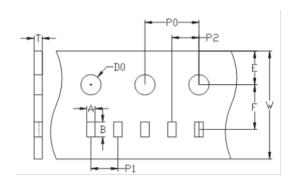


	Environmental Performance Characteristics	
Item	Test Condition	Specification
Short Time Overload	2.5X rated current for 5 seconds (JIS-C5202-5.5)	
Damp Heat with Load	Specimens shall be placed in a chamber and subject to a relative humidity of 90~95% and to a temperature of 40°C ± 2°C for the period of 1000 hours (MIL-STD_202, Method 103)	
High Temperature Exposure	Part (mounted on board) is exposed in the heat chamber 125°C ± 3°C for 1000 hours (JIS_C5202-7.2)	
Load Life	Apply rated power at 70°C ± 2°C for 1000 hours with 1.5 hours ON and 0.5 hour OFF (JIS_C5202-7.10)	
Rapid Change of Temperature	Part (mounted on board) is exposed, $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$ (30 min.)/+155 $\pm 2^{\circ}\text{C}$ (30 minutes) for 5 cycles. The following conditions as per picture below. (JIS_C5202-7.4) Ambient temperature 30 min. 30 min. 30 min. 2~3 min. 2~3 min. 2~3 min. 2~3 min. 2~3 min.	For 0402 size max. 0.003Ω All other sizes max. 0.0005Ω

Note: Test board surface temperature shall not exceed 100°C when applying rated current.

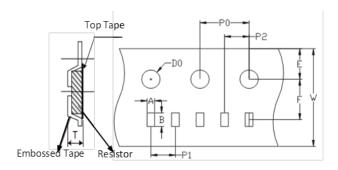
Storage Conditions: 5° C ~ 35° C. RH: 40%-75%

	Function Performance Characteristics	
Item	Test Condition	Specification
Bending Strength	Mount part to test substrate. Apply pressure in direction of arrow unit band width reaches 0.5mm (+0.2/-0mm)(illustrated in the figure below) and hold for 10 seconds ± 1 second. (JIS_C5202-6.1) Unit: mm Position before bend Testing printed circuit board	For 0402 size max. 0.003Ω All other sizes max. 0.0005Ω
Solvent Resistance	The part shall be completely immersed in the isopropyl alcohol for 3 minutes +0.5, -0 minutes, 25°C ±5°C (MIL_STD_202, Method 215)	Verify that marking remains. (Not required for laser etched parts or parts with no marking)
Resistance to Solder Heat	The part shall be immersed into the flux specified in the solder bath 260 °C ± 5 °C for 10 seconds ± 1 second (MIL_STD_202, Method 210)	For 0402 size max. 0.003Ω All other sizes max. 0.0005Ω
Solderability	The part shall be immersed into the flux specified in the solder bath 235°C ± 5°C for 2 seconds ± 0.5 seconds. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C 5202 6.11)	Solder shall be covered 95% or more of the electrode area



			Pac	kaging S	Specificat	ions – Pa	per Tape)			
Type / Code	А	В	E	F	W	P0	P1	P2	D0	Т	Unit
0402	0.028 ± 0.002	0.047 ± 0.002	0.069 ± 0.004	0.138 ± 0.002	0.315 ± 0.008	0.157 ± 0.004	0.079 ± 0.004	0.079 ± 0.002	0.061 ± 0.002	0.018 ± 0.004	inches
	0.70 ± 0.05	1.20 ± 0.05	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.10	2.00 ± 0.10	2.00 ± 0.05	1.55 ± 0.05	0.45 ± 0.10	mm
0603	0.043 ± 0.004	0.075 ± 0.004	0.069 ± 0.004	0.138 ± 0.002	0.315 ± 0.008	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.061 ± 0.002	0.025 ± 0.004	inches
	1.10 ± 0.10	1.90 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	1.55 ± 0.05	0.64 ± 0.10	mm
0805	0.063 ± 0.004	0.094 ± 0.004	0.069 ± 0.004	0.138 ± 0.002	0.315 ± 0.008	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.059 ± 0.002	0.038 ± 0.004	inches
	1.60 ± 0.10	2.40 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	1.50 ± 0.05	0.97 ± 0.10	mm
1206	0.079 ± 0.004	0.142 ± 0.004	0.069 ± 0.004	0.138 ± 0.002	0.315 ± 0.008	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.061 ± 0.002	0.038 ± 0.004	inches
	2.00 ± 0.10	3.60 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	1.55 ± 0.05	0.97 ± 0.10	mm

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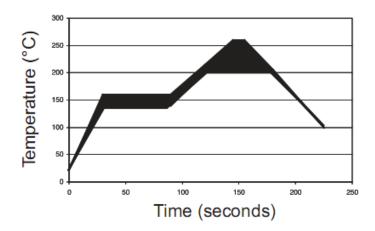


				Packagin	g Specific	cations –	Emboss	ed Plastic	Tape			
-	Type / Code	А	В	E	F	W	P0	P1	P2	D0	Т	Unit
	2512	0.138 ± 0.004 3.50 ± 0.10				0.472 ± 0.008 12.00 ± 0.20						inches mm

		Recom	mended Pad	Layout
Type / Code	а	b	С	Unit
0402	0.024	0.020	0.024	inches
	0.60	0.50	0.60	mm
0603	0.035	0.028	0.039	inches
	0.90	0.70	1.00	mm
0805	0.047	0.047	0.055	inches
	1.20	1.20	1.40	mm
1206	0.087	0.051	0.071	inches
	2.20	1.30	1.80	mm
2512	0.150	0.083	0.134	inches
	3.80	2.10	3.40	mm

Soldering Recommendations:

- Peak reflow temperatures and durations
 - ✓ IR Reflow Peak = 260°C max for 10 seconds
 - √ Wave Solder = 260°C max for 10 seconds
- · Compatible with lead and lead-free solder reflow processes
- Recommended IR reflow profile:



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